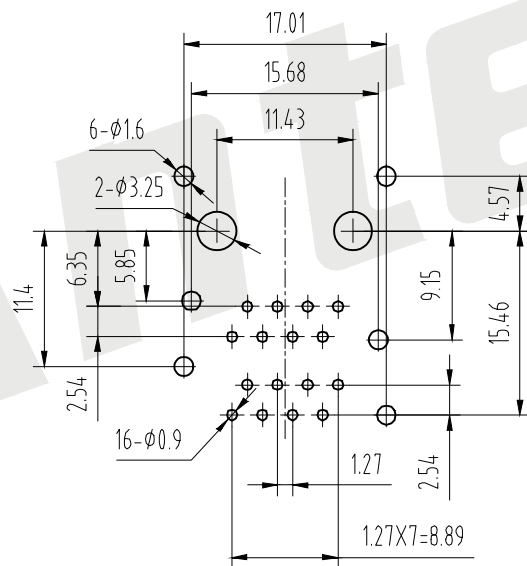
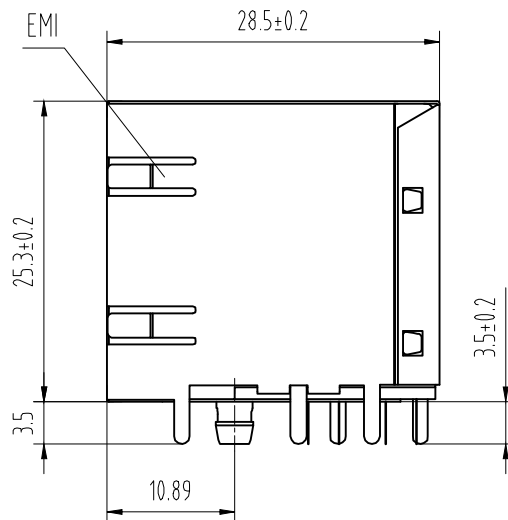
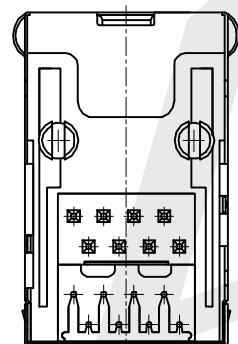
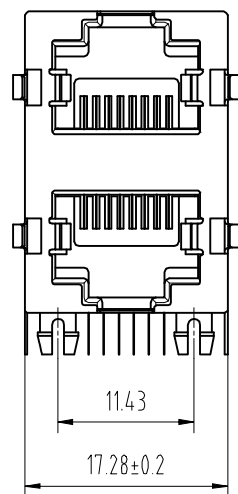


HSF



PC Board Layout

Component Side Shown

NOTES:
MATERIAL:

- HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
- CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
- PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
- SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

- VOLTAGE RATING: 125V AC RMS
- CURRENT RATING: 1.5AMP
- CONTACT RESISTANCE: 30 MILLIOHMS MAX
- INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
- DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

- DURRABILITY: 750 CYCLES MIN
- PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVIROMENTAL

- STORAGE: -40°C TO 85°C
- OPERATION: 0°C TO 70°C

Order code:

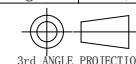
ATRJ5921 - 8P - 8C - X - C1 - G

① ② ③ ④ ⑤ ⑥

- | | |
|---|--------------------|
| ① SERIES NO: | ⑤ Shield |
| ② NUMBER OF POSITIONS (10P, 8P, 6P, 4P) | A: W/O Shield |
| ③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C) | B: Half Shield |
| ④ Contact Plating | C: Shield W/Eml |
| G0: Gold flash | D: Shield W/O Eml |
| ⑥ Ports | |
| G1: 3U" Gold | A: 1X1P G: 2*1P |
| G2: 5U" Gold | B: 1X2P H: 2*2P |
| G3: 10U" Gold | C: 1X4P I: 2*3P |
| G4: 15U" Gold | D: 1X5P J: 2*4P |
| G5: 30U" Gold | E: 1X6P K: 2*6P |
| SN: Tin | F: 1X8P L: 2*8P |

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 22/03/2018
CHECK BobYang DATE 22/03/2018



Antenk® ANTENK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE:
RJ45 Jack side entry full shielded 2X1P with EMI
DRAWING NO: ATRJ5921-8P8C-X-C1-G
PRODUCT NO: ATRJ5921-8P8C-X-C1-G

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		